

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJS8810A
Package Type :	TSSOP8

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	1.1022%
Lead Frame	Copper	7440-50-8	92.46%	49.6292%
	Iron	7439-89-6	2.50%	
	Lead	7439-92-1	0.01%	
	Phosphorus	7723-14-0	0.02%	
	Zinc	7440-66-6	0.02%	
	Silver	7440-22-4	5.00%	
Die Attach	Silver	7440-22-4	79.442%	3.7689%
	Acrylic resin	Trade secret	8.28%	
	Acrylate	Trade secret	3.14%	
	Polybutadiene	Trade secret	4.17%	
	Epoxy resin	Trade secret	2.21%	
	Butadiene copolymer	Trade secret	0.71%	
	Additive	Trade secret	1.14%	
	Peroxide	Trade secret	0.91%	
Wire1	copper	7440-50-8	99.99%	3.6262%
	others	/	0.01%	
Wire2	Cu	7440-50-8	97.90%	0.1127%
	Pd	7440-05-3	1.98%	
	Au	7440-57-5	0.12%	
Mold Compound	Epoxy Resin1	Trade secret	3.00%	40.7199%
	Epoxy Resin2	Trade secret	3.00%	
	Phenolic Resin	Trade secret	5.00%	
	catalyst	Trade secret	0.50%	
	Carbon Black	1333-86-4	0.30%	
	Amorphous silica 1	60676-86-0	80.00%	
	Amorphous silica 2	7631-86-9	8.20%	
Plating	Tin	7440-31-5	100.00%	1.041%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.